

Title (en)  
OPTICAL COMPONENT MOUNTING AND INTERCONNECT APPARATUS

Title (de)  
ANBRING- UND VERBINDUNGSVORRICHTUNG FÜR OPTISCHE KOMPONENTEN

Title (fr)  
APPAREIL DE MONTAGE ET D'INTERCONNEXION DE COMPOSANTS OPTIQUES

Publication  
**EP 1573825 A4 20060208 (EN)**

Application  
**EP 03786840 A 20031119**

Priority  
• US 0336930 W 20031119  
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Abstract (en)  
[origin: WO2004046766A2] Optoelectronic component mounting and interconnect apparatus is disclosed that includes an optoelectronic mounting plate with a substantially parallelepiped-shaped base plate having opposed major surfaces and a mounting edge extending between the major surfaces. A plurality of electrical contact pads are positioned on one of the major surfaces and electrically insulated from each other. One of the electrical contact pads is designed to have an optoelectronic device physically and electrically mounted thereon. A support plate is physically attached to the mounting edge and has electrical traces connected to at least some of the electrical contact pads. An optoelectronic component with two electrical contacts is mounted on a first contact pad with one contact connected to the pad and a second contact connected to a second pad.

IPC 8 full level  
**H01L 31/0203** (2006.01); **G02B 6/42** (2006.01); **H01L 23/48** (2006.01); **H01L 31/00** (2006.01); **H01L 31/0232** (2006.01); **H01S 5/022** (2006.01)

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C-Set (source: EP)  
**H01L 2924/0002 + H01L 2924/00**

Citation (search report)  
• [XY] EP 1154300 A2 20011114 - MITEL SEMICONDUCTOR AB [SE]  
• [X] EP 0924540 A1 19990623 - BOSCH GMBH ROBERT [DE]  
• [X] US 2002105042 A1 20020808 - KIM BRIAN H [US], et al  
• [YA] US 2002085256 A1 20020704 - AURACHER FRANZ [DE], et al  
• [A] US 2002106169 A1 20020808 - GO HISAO [JP]  
• [A] US 6477056 B1 20021105 - EDWARDS PHILLIP J [US], et al  
• See references of WO 2004046766A2

Designated contracting state (EPC)  
DE FR GB

DOCDB simple family (publication)  
**WO 2004046766 A2 20040603; WO 2004046766 A3 20041229**; AU 2003295639 A1 20040615; AU 2003295639 A8 20040615; CN 1711646 A 20051221; EP 1573825 A2 20050914; EP 1573825 A4 20060208

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